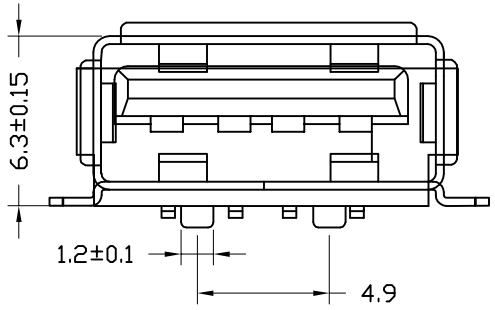
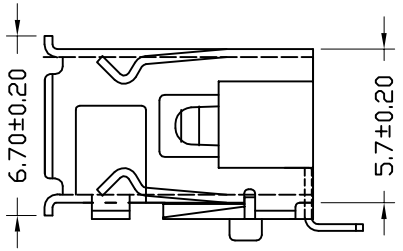
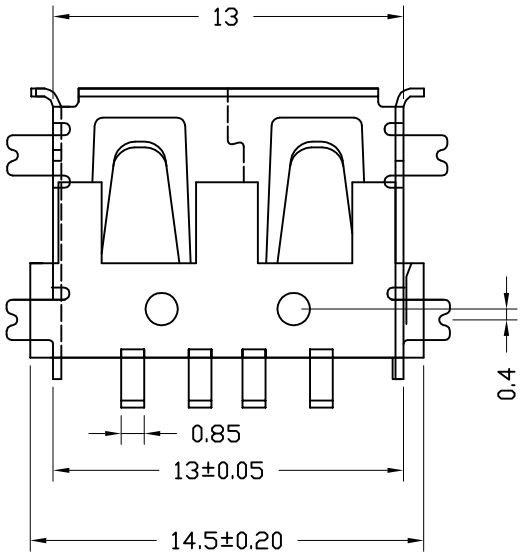
所有原料材质，生产制程，电镀必须符合RoHS要求

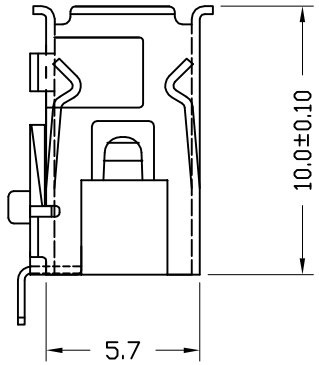
REV.	ECN NO.	LOCAS.	DESCRIPTION	DATE	DESIGN
A0			RELEASE TO CUSTOMER	150116	RYAN

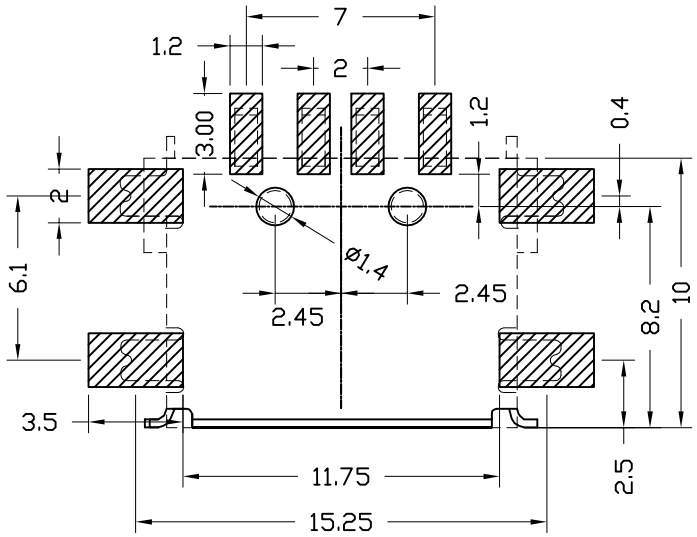
NOTES:
1. MATERIAL SPECIFCATION
1) INSULATION MATERIAL THERMOPLASTIC.
2) SHELL:COPPER ALLOY/SPCC,T:0.30mm
PLATING: NICKEL
3) TERMINAL:COPPER ALLOY,T:0.25mm
PLATING: GOLD/TIN PLATED.
2. ELECTRICAL CHARACTERISTIC:
1) INSULATION RESISTANCE:1000MΩ MIN.
2) CONTACT RESISTANCE:30mΩ MAX.
3) WITHSTANDING VOLTAGE:500V AC.
3. MECHANICAL CHARACTERISTICS:
1) INSERTION FORCE:3.57Kgf MAX.
2) EXTRACTION FORCE:1.02Kgf MIN.











RECOMMENDED PCB LAYOUT

DIM	TOL	DIM	TOL
X.	±0.30	X'.	±4.0'
X.X	±0.25	X.X'	±3.0'
X.XX	±0.20	X.XX'	±2.0'
X.XXX	±0.10	X.XXX'	±1.0'

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LASTAR Lastar Technology CO.,LTD

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DRAW NO.	112-G6B-04X7	DATE
DESIGN	RYAN	150116
CHECK	WANGCM	150116
APPROVED	HUYX	150116

DRAW NAME: USB A母 短体10.0MM H6.3 全贴卷边

P/N NO. USB-112-G6B-04X7 HS CODE

UNIT: mm SHEET: N/A MODEL X7

REV. A0 SCALE N/A